

BAP65LX

Silicon PIN diode

Rev. 3 — 11 December 2018 Product data sheet

1 Product profile

1.1 General description

Planar PIN diode in a SOD882D leadless ultra small plastic SMD package.

1.2 Features and benefits

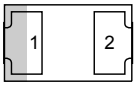
- High voltage, current controlled
- Low diode capacitance
- Low diode forward resistance (low loss)
- Very low series inductance
- RF resistor for RF switches
- AEC-Q101 qualified

1.3 Applications

- RF attenuators and switches
- Band switch for TV tuners
- Series diode for mobile communication transmit/receive switch

2 Pinning information

Table 1. Discrete pinning

Pin	Description		Simplified outline	Symbol
1	cathode	[1]	 Transparent top view	 sym006
2	anode			

[1] The marking bar indicates the cathode.

3 Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BAP65LX	DFN1006D-2	leadless ultra small plastic package; 2 terminals; body 1 × 0.6 × 0.4 mm	SOD882D

4 Marking

Table 3. Marking code

Type number	Marking code[1]
BAP65LX	1001 0110

[1] For SOD882D binary marking code description, see Figure 1.

4.1 Binary marking code description

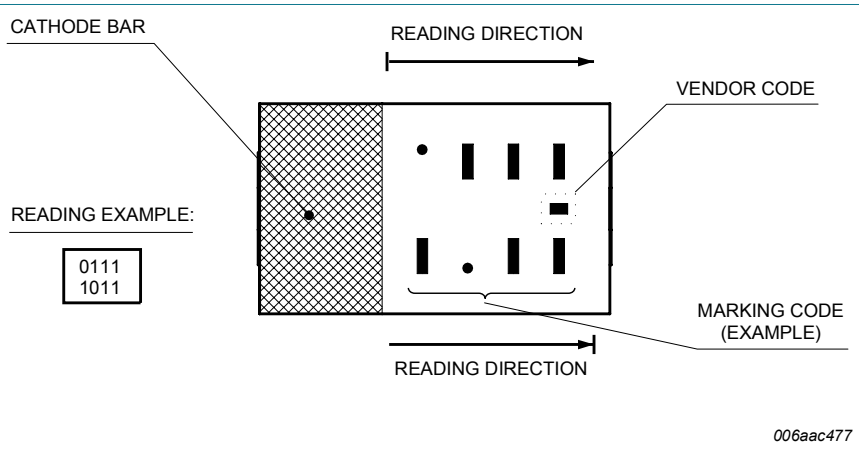


Figure 1. SOD882D binary marking code description example

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5 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	30	V
I_F	forward current		-	100	mA
P_{tot}	total power dissipation	$T_{sp} \leq 90$ °C	-	135	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-65	+150	°C

6 Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Typ	Unit
$R_{th(j\text{-}sp)}$	thermal resistance from junction to solder point			78	K/W

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7 Characteristics

Table 6. Characteristics

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	I_F = 50 mA	-	0.9	1.1	V
I_R	reverse current	V_R = 20 V	-	-	20	nA
C_d	diode capacitance	f = 1 MHz (Figure 2)				
		V_R = 0 V	-	0.61	-	pF
		V_R = 1 V	-	0.48	0.85	pF
		V_R = 3 V	-	0.43	0.7	pF
		V_R = 20 V	-	0.37	-	pF
r_D	diode forward resistance	f = 100 MHz (Figure 3)				
		I_F = 1 mA	-	0.94	-	Ω
		I_F = 5 mA	-	0.58	0.95	Ω
		I_F = 10 mA	-	0.49	0.9	Ω
		I_F = 100 mA	-	0.35	-	Ω
ISL	isolation	V_R = 0 V (Figure 5)				
		f = 900 MHz	-	10	-	dB
		f = 1800 MHz	-	5.5	-	dB
		f = 2450 MHz	-	3.9	-	dB
L_{ins}	insertion loss	See Figure 4.				
		I_F = 1 mA;				
		f = 900 MHz	-	0.09	-	dB
		f = 1800 MHz	-	0.09	-	dB
		f = 2450 MHz	-	0.10	-	dB
		I_F = 5 mA;				
		f = 900 MHz	-	0.06	-	dB
		f = 1800 MHz	-	0.07	-	dB
		f = 2450 MHz	-	0.08	-	dB

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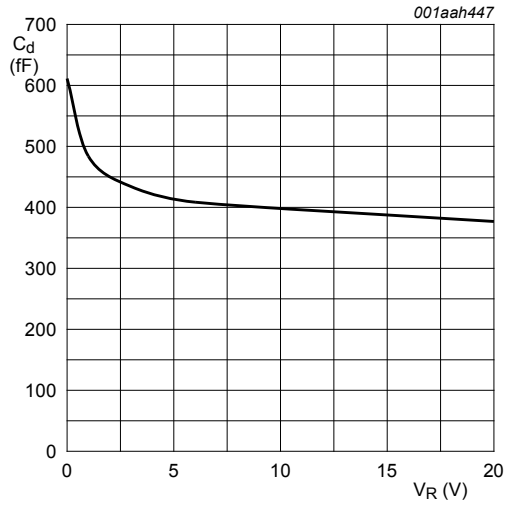
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Symbol	Parameter	Conditions	Min	Typ	Max	Unit
L_{ins}	insertion loss	I_F = 10 mA;				
		f = 900 MHz	-	0.06	-	dB
		f = 1800 MHz	-	0.07	-	dB
		f = 2450 MHz	-	0.08	-	dB
		I_F = 100 mA;				
		f = 900 MHz	-	0.05	-	dB
		f = 1800 MHz	-	0.06	-	dB
		f = 2450 MHz	-	0.07	-	dB
τ_L	charge carrier life time	when switched from I_F = 10 mA to I_R = 6 mA; R_L = 100 Ω; measured at I_R = 3 mA	-	0.18	-	µs
L_S	series inductance	I_F = 100 mA; f = 100 MHz	-	0.4	-	nH

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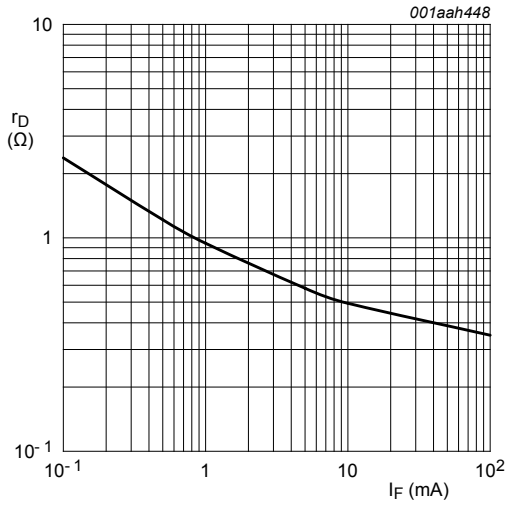
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8 Graphical data



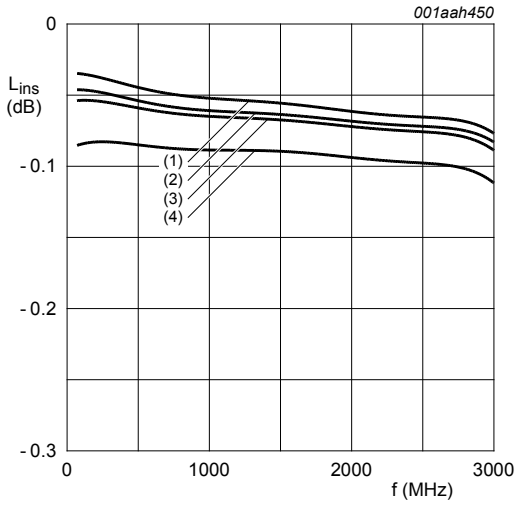
f = 1 MHz; T_j = 25 °C.

Figure 2. Diode capacitance as a function of reverse voltage (typical values)



f = 100 MHz; T_j = 25 °C.

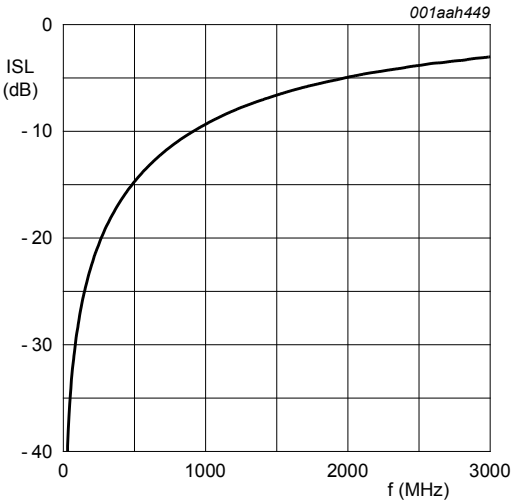
Figure 3. Forward resistance as a function of forward current (typical values)



Diode inserted in series with a 50 Ω strip line circuit and biased via the analyzer T-network. T_{amb} = 25 °C

(1) I_F = 100 mA
(2) I_F = 10 mA
(3) I_F = 5 mA
(4) I_F = 1 mA

Figure 4. Insertion loss of the diode in on-state as a function of frequency (typical values)



Diode zero biased and inserted in series with a 50 Ω strip line circuit. T_{amb} = 25 °C.

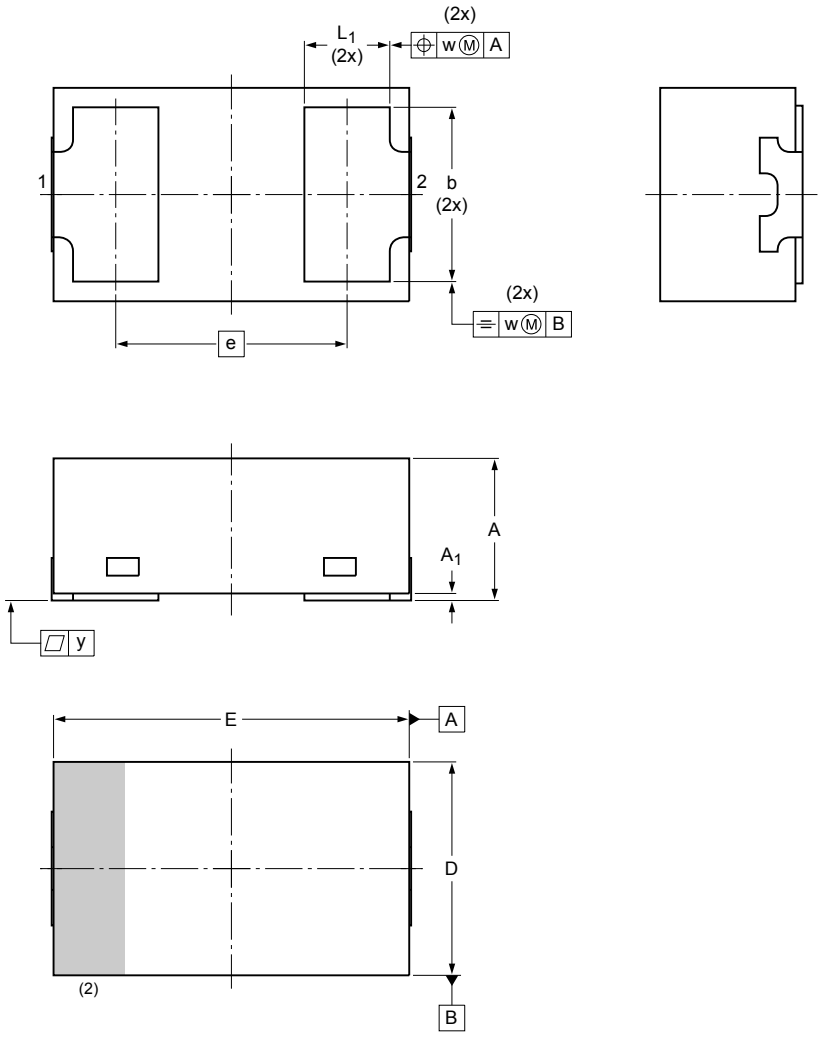
Figure 5. Isolation of the diode in off-state as a function of frequency (typical values)

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9 Package outline

DFN1006D-2: Leadless ultra small plastic package; 2 terminals; body 1 x 0.6 x 0.4 mm **SOD882D**



Dimensions

Unit		$A^{(1)}$	A_1	b	D	E	e	L_1	w	y
mm	max	0.4	0.04	0.55	0.65	1.05		0.30	0.1	0.03
	nom			0.50	0.60	1.00	0.65	0.25		
	min			0.45	0.55	0.95		0.22		

0 0.5 1 mm
scale

Note
1. Dimension including plating thickness.
2. The marking bar indicates the cathode (if applicable).

sod882d_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOD882D						~~10-09-27~~ 12-05-01

Figure 6. Package outline SOD882D (DFN1006D-2)

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10 Abbreviations

Table 7. Abbreviations

Acronym	Description
PIN	P-type, intrinsic, N-type
SMD	surface-mounted device
RF	radio frequency

11 Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP65LX v.3	20181211	Product data sheet	-	BAP65LX v.2
Modifications:	• Section 1.2 "Features and benefits" has been updated. • The "Legal information" pages have been updated.			
BAP65LX v.2	20130807	Product data sheet	-	BAP65LX v.1
BAP65LX v.1	20071211	Product data sheet	-	-

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12 Legal information

12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 11 December 2018
Document identifier: BAP65LX